

L Number	Hits	Search Text	DB	Time stamp
1	2740	((housing enclosure) near5 mold\$3 with (conductive metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 13:48
2	1074	((housing enclosure) near5 mold\$3 with (conductive metal)) and connector	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 13:49
3	484	((housing enclosure) near5 mold\$3 with (conductive metal)) same connector	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/10 13:55
4	1147	(polymer) near5 ((load\$2 fill\$2) near5 (conductive))	USPAT	2003/02/10 14:23
6	1	((polymer) near5 ((load\$2 fill\$2) near5 (conductive))) with mold\$4 and connector	USPAT	2003/02/10 13:57
5	37	((polymer) near5 ((load\$2 fill\$2) near5 (conductive))) with mold\$4	USPAT	2003/02/10 13:58
7	38	(liquid near2 crystal) near5 ((load\$2 fill\$2) near5 (conductive))	USPAT	2003/02/10 14:29
8	8	(liquid near2 crystal near3 polymer) near5 ((load\$2 fill\$2) near5 (conductive))	USPAT	2003/02/10 14:45
9	3	(liquid near2 crystal near3 polymer) near5 ((load\$2 fill\$2) with (conductive))	USPAT	2003/02/10 14:36
10	0	(liquid near2 crystal near3 polymer) near5 ((load\$2 fill\$2) with ((carbon near1 fiber) or aluminum or copper or (boron near1 nitride) or alumina or magnesium or brass))	USPAT	2003/02/10 14:42
11	0	(liquid near4 polymer) near5 ((load\$2 fill\$2) with ((carbon near1 fiber) or aluminum or copper or (boron near1 nitride) or alumina or magnesium or brass))	USPAT	2003/02/10 14:42
12	228	(liquid near2 crystal near3 polymer) near5 (load\$2 fill\$2)	USPAT	2003/02/10 14:43
13	13	((liquid near2 crystal near3 polymer) near5 (load\$2 fill\$2)) same connector	USPAT	2003/02/10 14:43
14	3	(liquid near2 crystal near3 polymer) near8 ((load\$2 fill\$2) with (conductive))	USPAT	2003/02/10 14:46